



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260701000.1	PCN Issued	July 02, 2026
Qualification of RFAB site for select devices		Sample request deadline:	August 31, 2026
		Estimated 1st ship date:	September 30, 2026
August 31, 2026* will not be supported.			

Change type(s)
Packing/Shipping/Labeling
Wafer Fab Site
Wafer Fab Material
Wafer Fab Process

PCN Details

Description of Change:					
Texas Instruments is pleased to announce the qualification of RFAB site for select devices.					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
FFAB	LBC7	200mm	RFAB	LBC7	300mm
Qual details are provided in the Qual Data Section.					
Reason for Change:		Supply continuity			

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Review the Standard Data Packet for more details on the changes															
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table><tr><td>RoHS</td><td>REACH</td><td>Green Status</td><td>IEC 62474</td></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>				RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change				
RoHS	REACH	Green Status	IEC 62474													
☒ No Change	☒ No Change	☒ No Change	☒ No Change													
Changes to product identification resulting from this PCN:	Fab Site Information <table><tr><td>Chip Site</td><td>Chip Site Origin Code (20L)</td><td>Chip Site Country Code (21L)</td><td>Chip Site City</td></tr><tr><td>FFAB</td><td>TID</td><td>DEU</td><td>Freising</td></tr><tr><td>RFAB</td><td>RFB</td><td>USA</td><td>Richardson</td></tr></table>				Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	FFAB	TID	DEU	Freising	RFAB	RFB	USA	Richardson
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City													
FFAB	TID	DEU	Freising													
RFAB	RFB	USA	Richardson													

	Sample product shipping label (not actual product label):
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Products Affected:			
TPS61240DRVR			

Product Attributes

Attributes	Qual Device: TPS63020QDSJRQ1	Qual Device: TPS61240TDRVRQ1	QBS Process Reference: TPS652510QRHARQ1
Automotive Grade Level	Grade 1	Grade 2	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 105	-40 to 125
Product Function	Logic	Logic	Power Management
Wafer Fab Supplier	RFAB	RFAB	RFAB
Assembly Site	CLARK-AT	CDAT	CLARK-AT
Package Group	QFN	QFN	QFN
Package Designator	DSJ	DRV	RHA
Pin Count	14	6	40

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TPS63020QDSJRQ1 is qualified at MSL2 260C
- Qual Device TPS61240TDRVRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS63020QDSJRQ1	Qual Device: TPS61240TDRVRQ1	QBS Process Reference: TPS652510QRHARQ1
Test Group A - Accelerated Environment Stress Tests										
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	110C/85%RH	264 Hours	-	-	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	110C/85%RH	264 Hours	-	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests										
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	3/231/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0
Test Group C - Package Assembly Integrity Tests										
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0
Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: TPS63020QDSJRQ1	Qual Device: TPS61240TDRVRQ1	QBS Process Reference: TPS652510QRHARQ1
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0
Test Group D - Die Fabrication Reliability Tests										
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Tddb	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests										
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	1000 Volts	1/3/0	-	-
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	1/3/0	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	-	-

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device:	Qual Device:	QBS Process Reference:
								<u>TPS63020QPSJRQ1</u>	<u>TPS61240TDRVRQ1</u>	<u>TPS652510QRHARQ1</u>
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1000 Volts	-	1/3/0	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	1/3/0	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	1/30/0	1/30/0	3/90/0
Additional Tests										
BLR	T1	-	-	-	Board Level Reliability - Temp Cycle	-40/125C	1000 Cycles	-	-	1/32/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-100

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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